

PCN Number:	201500306000	PCN Date:	03/09/2015
Title:	Datasheet update for OPA192		
Customer Contact:	PCN Manager	Dept:	Quality Services
Proposed 1st Ship Date:	06/09/2015		
Change Type:			
<input type="checkbox"/>	Assembly Site	<input type="checkbox"/>	Design
<input type="checkbox"/>	Assembly Process	<input checked="" type="checkbox"/>	Data Sheet
<input type="checkbox"/>	Assembly Materials	<input type="checkbox"/>	Part number change
<input type="checkbox"/>	Mechanical Specification	<input type="checkbox"/>	Test Site
<input type="checkbox"/>	Packing/Shipping/Labeling	<input type="checkbox"/>	Test Process
		<input type="checkbox"/>	Wafer Bump Site
		<input type="checkbox"/>	Wafer Bump Material
		<input type="checkbox"/>	Wafer Bump Process
		<input type="checkbox"/>	Wafer Fab Site
		<input type="checkbox"/>	Wafer Fab Materials
		<input type="checkbox"/>	Wafer Fab Process

PCN Details

Description of Change:

The product datasheet(s) is being updated as summarized below.

The following change history provides further details:



OPA192, OPA2192, OPA4192

SBOS620B – DECEMBER 2013 – REVISED MARCH 2015

www.ti.com

Changes from Revision A (January 2014) to Revision B

Page

• Added ESD Ratings and Recommended Operating Conditions tables, and <i>Parameter Measurement Information, Application and Implementation, Power-Supply Recommendations, and Device and Documentation Support</i> sections, and moved existing sections	1
• Changed all OPA192 and OPA2192 packages to production data	1
• Changed package names to latest standard; changed all MSOP to VSSOP, SO to SOIC, and SOT23 to SOT	1
• Deleted DCK package pin configuration	4
• Added thermal information for OPA192 DBV and DGK packages	6
• Added OPA2192 and OPA4192 Thermal Information tables	7
• Added rows with additional test conditions to input offset voltage parameter	7
• Changed Input offset voltage drift parameter	7
• Changed CMRR test conditions	8
• Added rows with additional test conditions to input offset voltage parameter	9
• Changed Input offset voltage drift parameter	9
• Changed PSSR parameter	9
• Changed CMRR test conditions	9
• Added <i>Output</i> section	10
• Added typical characteristic curves to Table 1	11
• Added T _A = 25°C to Typical Characteristics condition line	11
• Added nine new histogram plots from Figure 2 to Figure 10	12
• Changed Figure 11 to show more units	12
• Changed Figure 19	14
• Added text to <i>Application Information</i> section	30
• Changed text in <i>Layout Guidelines</i> section	34

The datasheet number will be changing.

Device Family	Change From:	Change To:
OPA192	SBOS620A	SBOS620B

These changes may be reviewed at the datasheet links provided.

<http://www.ti.com/product/opa192>

Reason for Change:	
To more accurately reflect device characteristics.	
Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):	
To more accurately reflect device characteristics.	
Changes to product identification resulting from this PCN:	
None.	
Product Affected:	
OPA192ID	OPA192IDR

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com